

## BYV28 series

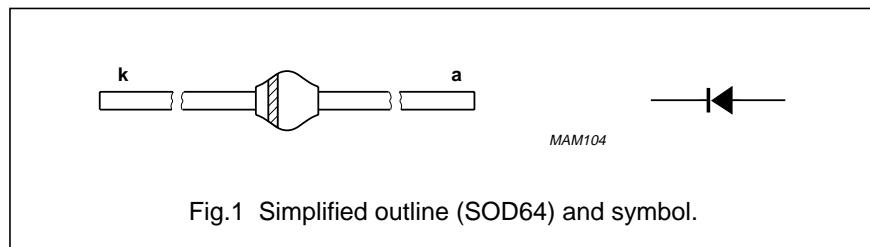
### FEATURES

- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Guaranteed avalanche energy absorption capability
- Available in ammo-pack
- Also available with preformed leads for easy insertion.

### DESCRIPTION

Rugged glass SOD64 package, using a high temperature alloyed construction.

This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.



MAM104

Fig.1 Simplified outline (SOD64) and symbol.

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{RRM}$	repetitive peak reverse voltage BYV28-50		–	50	V
	BYV28-100			100	V
	BYV28-150			150	V
	BYV28-200			200	V
	BYV28-300			300	V
	BYV28-400			400	V
	BYV28-500			500	V
	BYV28-600			600	V
$V_R$	continuous reverse voltage BYV28-50		–	50	V
	BYV28-100			100	V
	BYV28-150			150	V
	BYV28-200			200	V
	BYV28-300			300	V
	BYV28-400			400	V
	BYV28-500			500	V
	BYV28-600			600	V
$I_{F(AV)}$	average forward current BYV28-50 to 400	$T_{tp} = 85^\circ\text{C}$ ; lead length = 10 mm; see Figs 2 and 3; averaged over any 20 ms period; see also Figs 10 and 11	–	3.5	A
	BYV28-500 and 600			3.1	A
$I_{F(AV)}$	average forward current BYV28-50 to 400	$T_{amb} = 60^\circ\text{C}$ ; printed-circuit board mounting (see Fig.20); see Figs 4 and 5; averaged over any 20 ms period; see also Figs 10 and 11	–	1.9	A
	BYV28-500 and 600			1.5	A



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SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$I_{FRM}$	repetitive peak forward current BYV28-50 to 400 BYV28-500 and 600	$T_{tp} = 85^\circ\text{C}$ ; see Figs 6 and 7	—	32 31	A A
$I_{FRM}$	repetitive peak forward current BYV28-50 to 400 BYV28-500 and 600	$T_{amb} = 60^\circ\text{C}$ ; see Figs 8 and 9	—	17 16	A A
$I_{FSM}$	non-repetitive peak forward current	$t = 10 \text{ ms half sine wave};$ $T_j = T_{j\max}$ prior to surge; $V_R = V_{RRMmax}$	—	90	A
$E_{RSM}$	non-repetitive peak reverse avalanche energy	$L = 120 \text{ mH}; T_j = T_{j\max}$ prior to surge; inductive load switched off	—	20	mJ
$T_{stg}$	storage temperature		—65	+175	°C
$T_j$	junction temperature	see Fig.12	—65	+175	°C

## ELECTRICAL CHARACTERISTICS

 $T_j = 25^\circ\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_F$	forward voltage BYV28-50 to 200 BYV28-300 and 400 BYV28-500 and 600	$I_F = 3.5 \text{ A}; T_j = T_{j\max}$ ; see Figs 13, 14 and 15	— — —	— — —	0.80 0.83 0.98	V V V
$V_F$	forward voltage BYV28-50 to 200 BYV28-300 and 400 BYV28-500 and 600	$I_F = 3.5 \text{ A};$ see Figs 13, 14 and 15	— — —	— — —	1.02 1.05 1.25	V V V
$V_{(BR)R}$	reverse avalanche breakdown voltage BYV28-50 BYV28-100 BYV28-150 BYV28-200 BYV28-300 BYV28-400 BYV28-500 BYV28-600	$I_R = 0.1 \text{ mA}$	55 110 165 220 330 440 560 675	— — — — — — — —	— — — — — — — —	V V V V V V V V
$I_R$	reverse current	$V_R = V_{RRMmax}$ ; see Fig.16	—	—	5	$\mu\text{A}$
		$V_R = V_{RRMmax}; T_j = 165^\circ\text{C}$ ; see Fig.16	—	—	150	$\mu\text{A}$
$t_{rr}$	reverse recovery time BYV28-50 to 200 BYV28-300 to 600	when switched from $I_F = 0.5 \text{ A}$ to $I_R = 1 \text{ A}$ ; measured at $I_R = 0.25 \text{ A}$ ; see Fig.22	— —	— —	25 50	ns ns

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$C_d$	diode capacitance BYV28-50 to 200	$f = 1 \text{ MHz}; V_R = 0;$ see Figs 17, 18 and 19	–	190	–	pF
	BYV28-300 and 400			150	–	pF
	BYV28-500 and 600			125	–	pF
$ \frac{dI_R}{dt} $	maximum slope of reverse recovery current	when switched from $I_F = 1 \text{ A}$ to $V_R \geq 30 \text{ V}$ and $dI_F/dt = -1 \text{ A}/\mu\text{s}$ ; see Fig.21	–	–	4	A/ $\mu\text{s}$

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th j\text{-tp}}$	thermal resistance from junction to tie-point	lead length = 10 mm	25	K/W
$R_{th j\text{-a}}$	thermal resistance from junction to ambient	note 1	75	K/W

### Note

1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer  $\geq 40 \mu\text{m}$ , see Fig.20  
For more information please refer to the "General Part of associated Handbook".

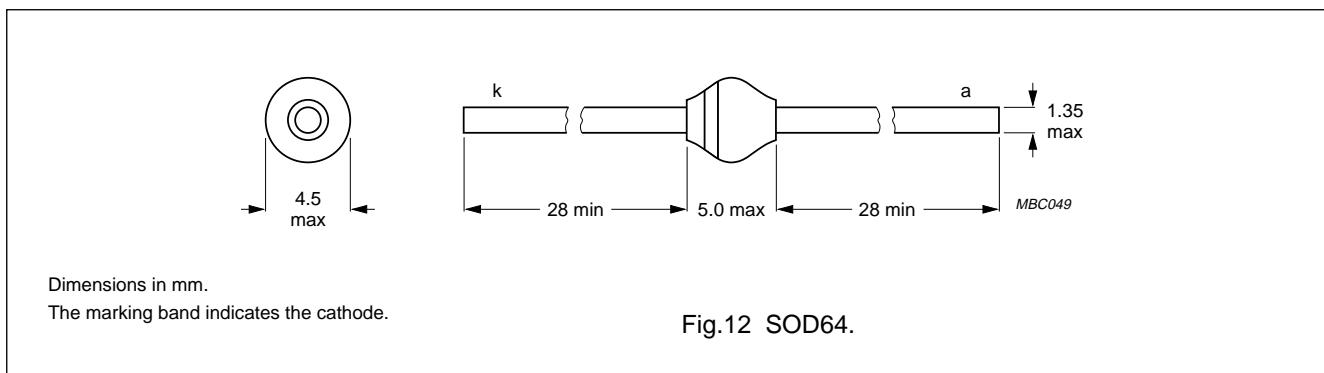
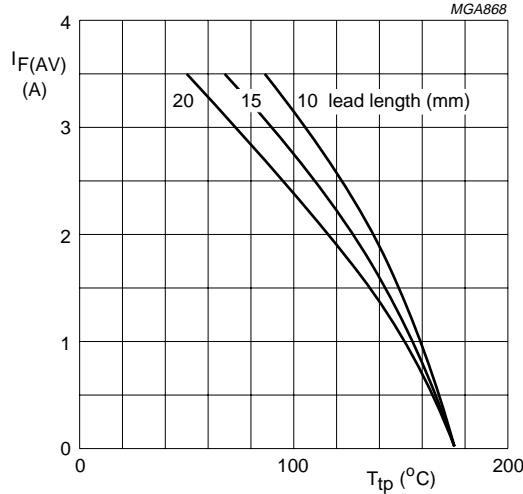


Fig.12 SOD64.

## BYV28 series

### GRAPHICAL DATA

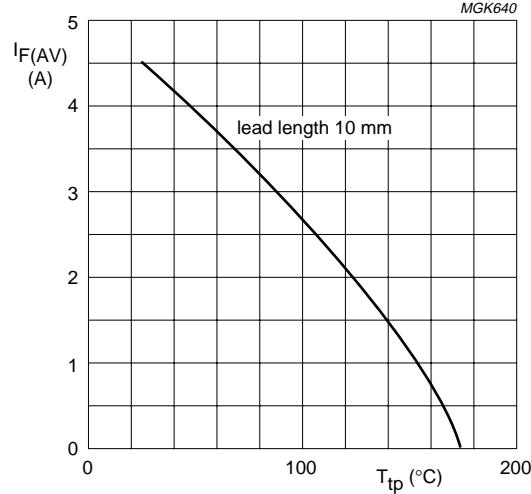


**BYV28-50 to 400**

a = 1.42; V<sub>R</sub> = V<sub>RRMmax</sub>; δ = 0.5.

Switched mode application.

Fig.2 Maximum permissible average forward current as a function of tie-point temperature (including losses due to reverse leakage).

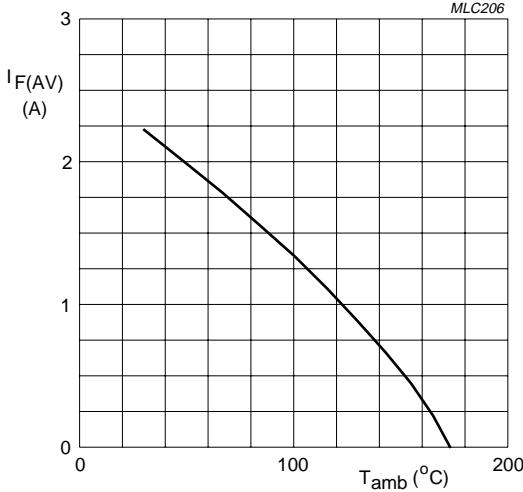


**BYV28-500 and 600**

a = 1.42; V<sub>R</sub> = V<sub>RRMmax</sub>; δ = 0.5.

Switched mode application.

Fig.3 Maximum permissible average forward current as a function of tie-point temperature (including losses due to reverse leakage).

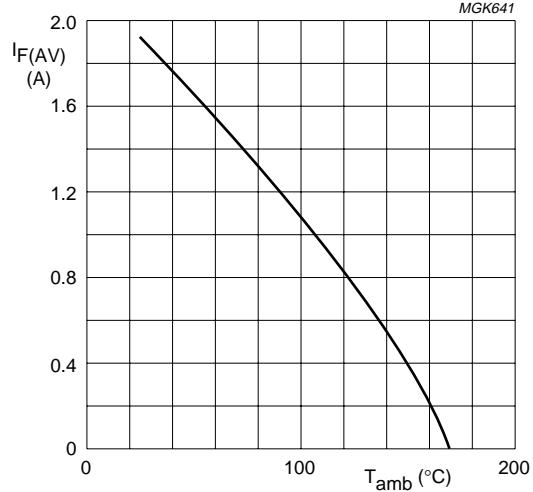


**BYV28-50 to 400**

a = 1.42; V<sub>R</sub> = V<sub>RRMmax</sub>; δ = 0.5; switched mode application.

Device mounted as shown in Fig.20.

Fig.4 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).



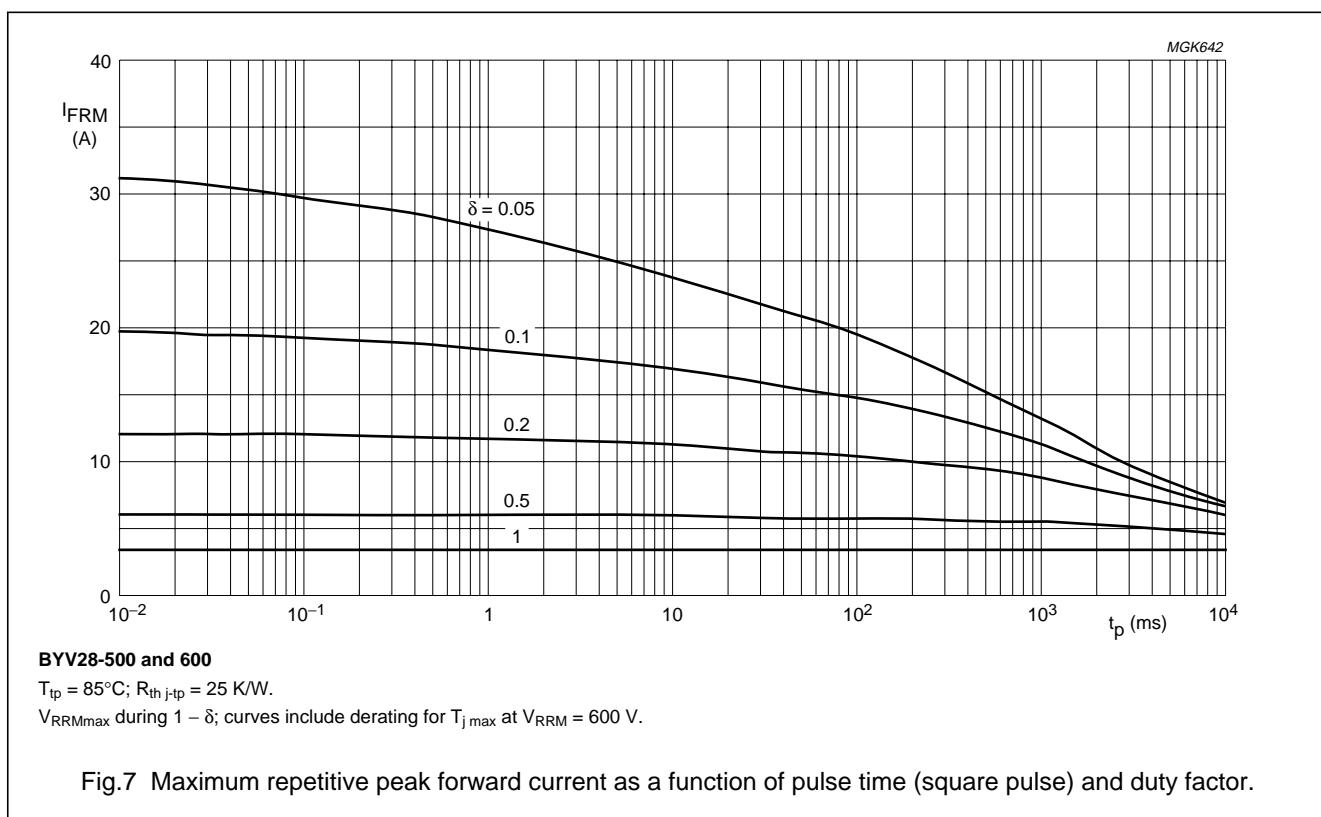
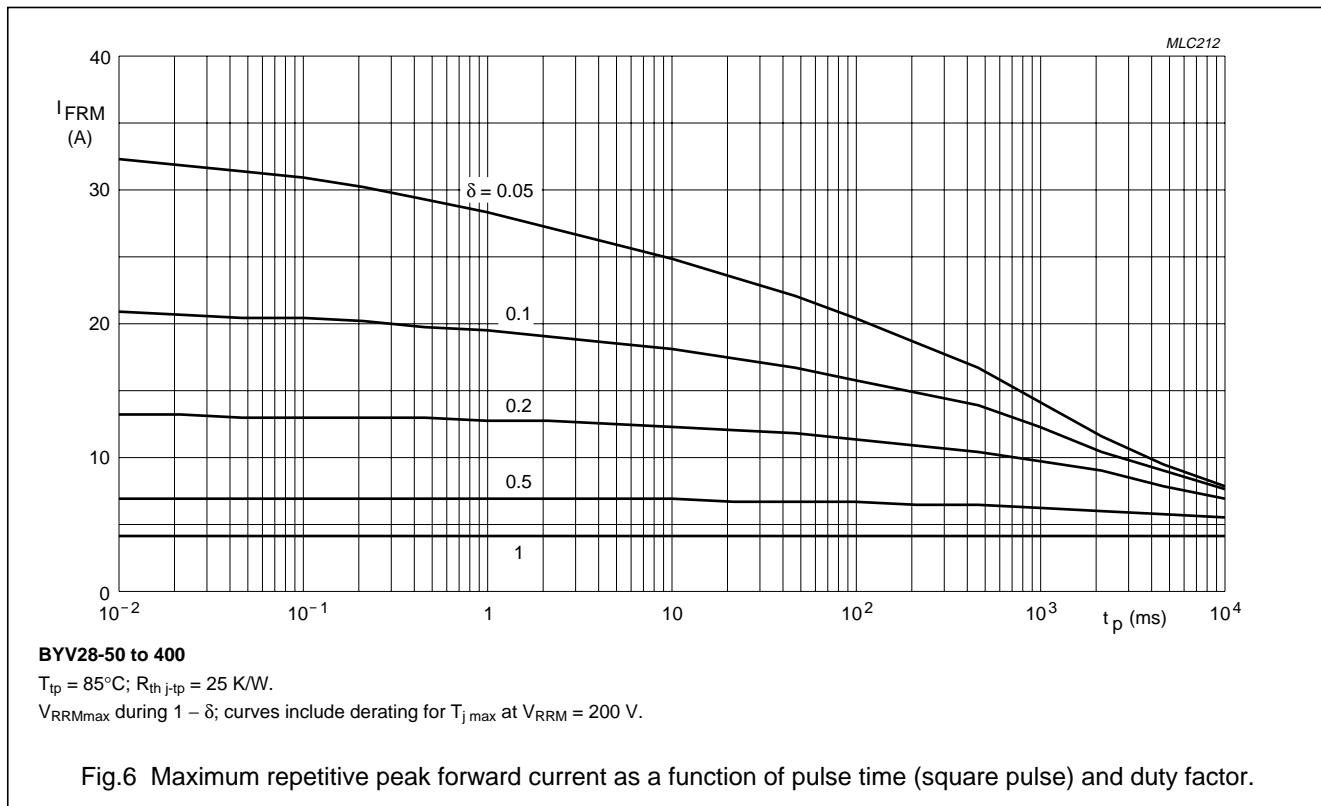
**BYV28-500 and 600**

a = 1.42; V<sub>R</sub> = V<sub>RRMmax</sub>; δ = 0.5; switched mode application.

Device mounted as shown in Fig.20.

Fig.5 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).

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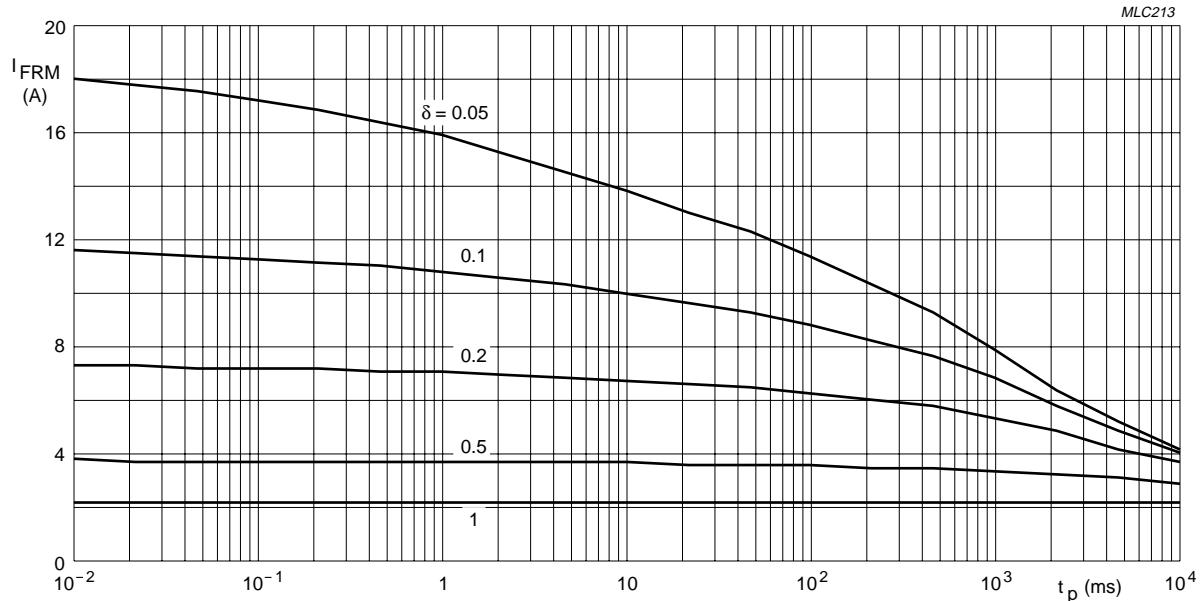
**BYV28 series**

**BYV28-50 to 400**
 $T_{amb} = 60 \text{ }^{\circ}\text{C}; R_{th\ j-a} = 75 \text{ K/W.}$ 
 $V_{RRMmax}$  during  $1 - \delta$ ; curves include derating for  $T_{j\ max}$  at  $V_{RRM} = 200 \text{ V.}$ 

Fig.8 Maximum repetitive peak forward current as a function of pulse time (square pulse) and duty factor.

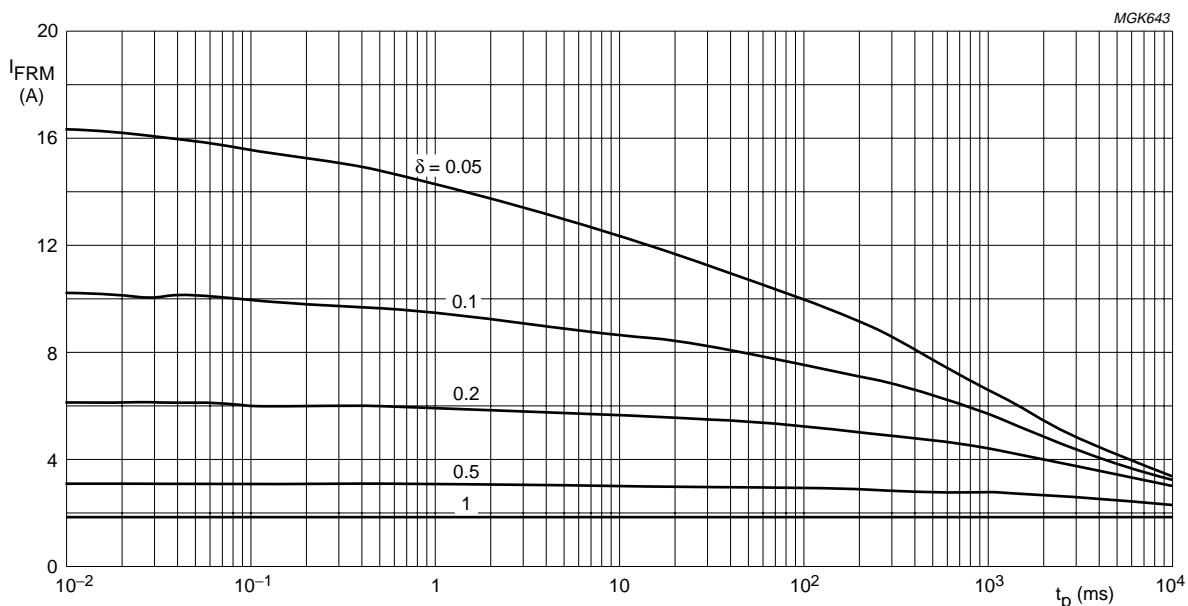

**BYV28-500 and 600**
 $T_{amb} = 60 \text{ }^{\circ}\text{C}; R_{th\ j-a} = 75 \text{ K/W.}$ 
 $V_{RRMmax}$  during  $1 - \delta$ ; curves include derating for  $T_{j\ max}$  at  $V_{RRM} = 600 \text{ V.}$ 

Fig.9 Maximum repetitive peak forward current as a function of pulse time (square pulse) and duty factor.

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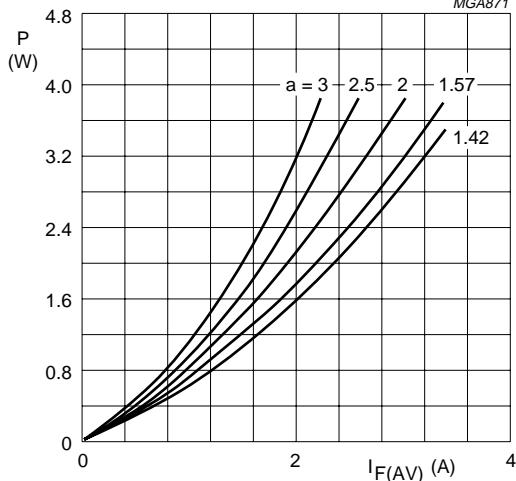

**BYV28-50 to 400**
 $a = I_{F(RMS)} / I_{F(AV)}$ ;  $V_R = V_{RRMmax}$ ;  $\delta = 0.5$ .

Fig.10 Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.

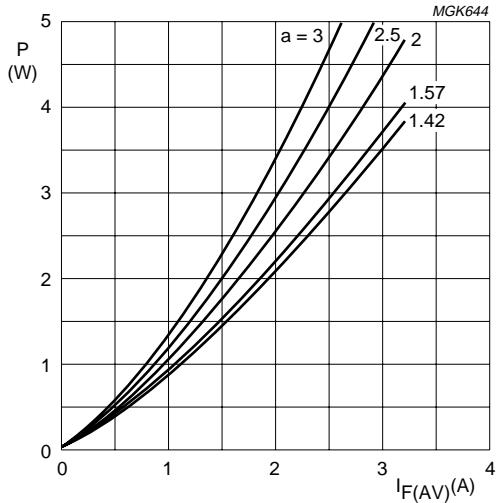
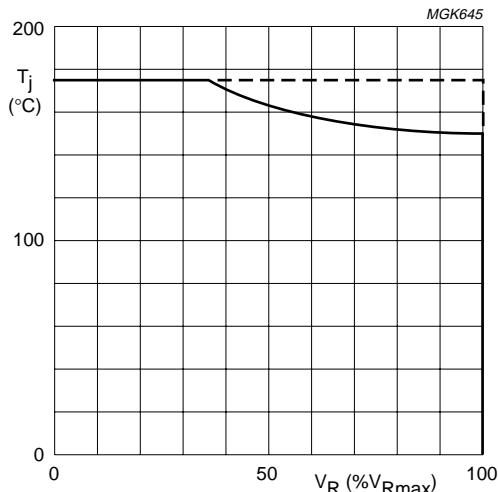
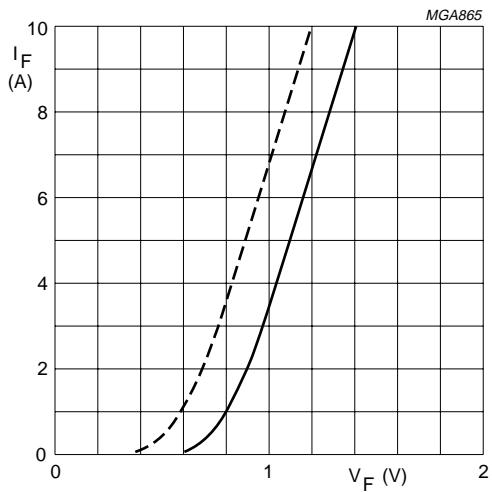

**BYV28-500 and 600**
 $a = I_{F(RMS)} / I_{F(AV)}$ ;  $V_R = V_{RRMmax}$ ;  $\delta = 0.5$ .

Fig.11 Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.


Solid line =  $V_R$ .

Dotted line =  $V_{RRM}$ ;  $\delta = 0.5$ .

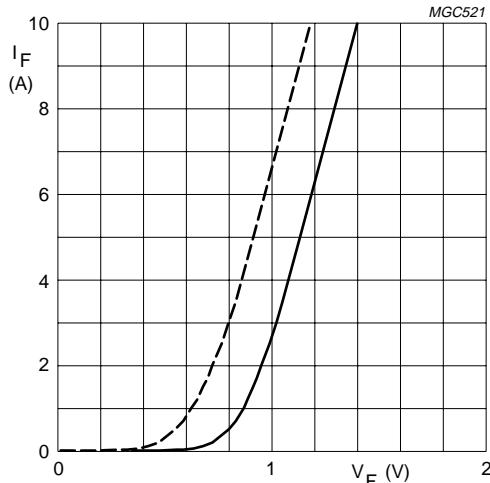
Fig.12 Maximum permissible junction temperature as a function of maximum reverse voltage percentage.


**BYV28-50 to 200**

Dotted line:  $T_j = 175$  °C.

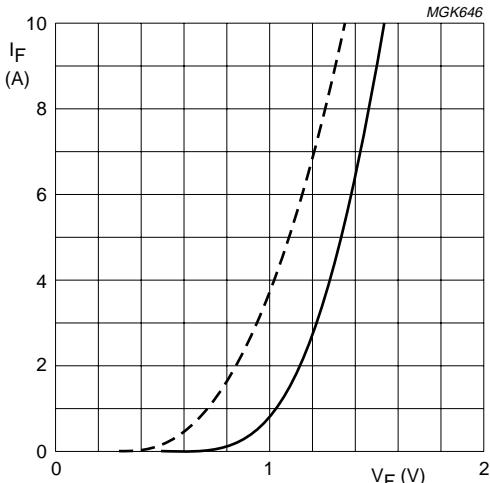
Solid line:  $T_j = 25$  °C.

Fig.13 Forward current as a function of forward voltage; maximum values.

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**BYV28-300 and 400**

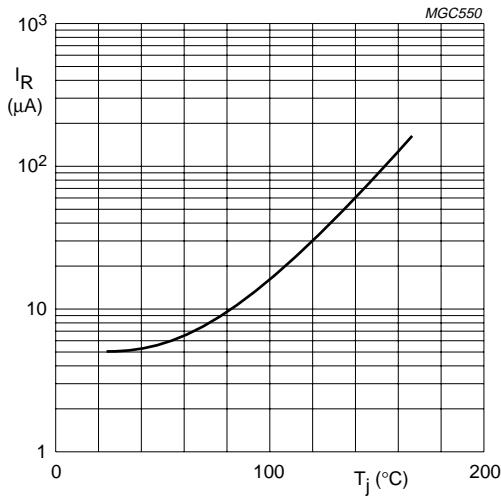
Dotted line:  $T_j = 175 \text{ }^\circ\text{C}$ .  
 Solid line:  $T_j = 25 \text{ }^\circ\text{C}$ .

Fig.14 Forward current as a function of forward voltage; maximum values.


**BYV28-500 and 600**

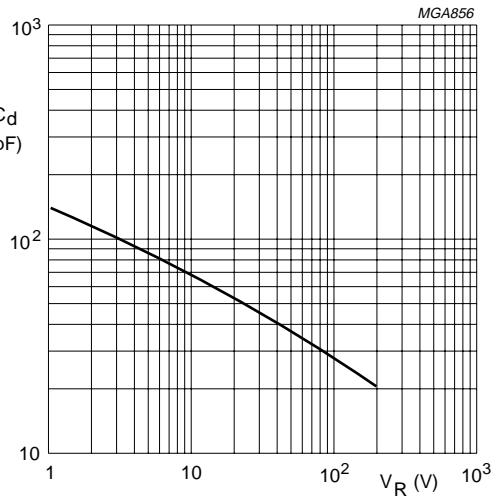
Dotted line:  $T_j = 175 \text{ }^\circ\text{C}$ .  
 Solid line:  $T_j = 25 \text{ }^\circ\text{C}$ .

Fig.15 Forward current as a function of forward voltage; maximum values.



$V_R = V_{RRMmax}$ .

Fig.16 Reverse current as a function of junction temperature; maximum values.



**BYV28-50 to 200**  
 $f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$ .

Fig.17 Diode capacitance as a function of reverse voltage; typical values.

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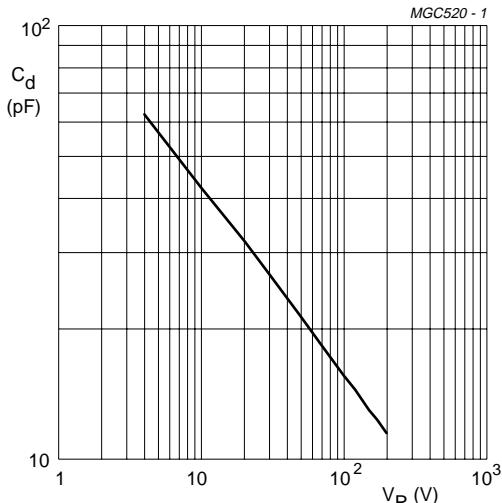

**BYV28-300 and 400**
 $f = 1 \text{ MHz}; T_j = 25^\circ\text{C}.$ 

Fig.18 Diode capacitance as a function of reverse voltage; typical values.

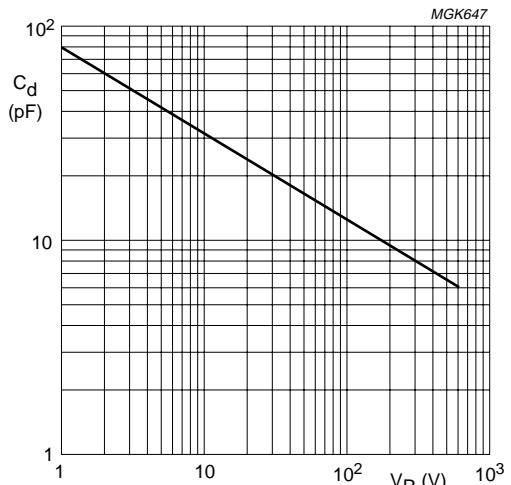
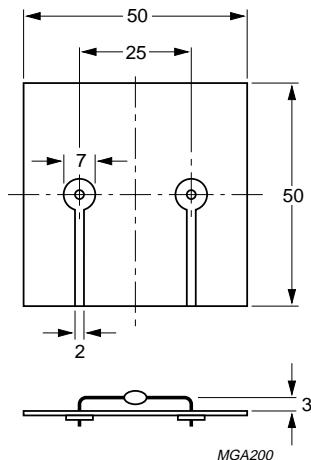

**BYV28-500 and 600**
 $f = 1 \text{ MHz}; T_j = 25^\circ\text{C}.$ 

Fig.19 Diode capacitance as a function of reverse voltage; typical values.



Dimensions in mm.

Fig.20 Device mounted on a printed-circuit board.

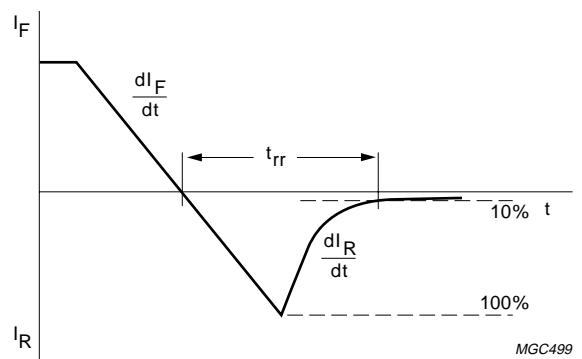


Fig.21 Reverse recovery definitions.